

SECURITIES AND EXCHANGE COMMISSION
Washington, DC 20549

REPORT OF FOREIGN PRIVATE ISSUER
PURSUANT TO RULE 13a-16 OR 15d-16 OF

THE SECURITIES EXCHANGE ACT OF 1934

For the month of April 2000

STMicroelectronics N.V.

(Translation of registrant's name into English)

Route de Pre-Bois, ICC Bloc A, 1215 Geneva 15, Switzerland

(Address of principal executive offices)

[Indicate by check mark whether the registrant files or will file
annual reports under cover of Form 20-F or Form 40-F]

Form 20-F Form 40-F
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[Indicate by check mark whether the registrant by furnishing the
information contained in this Form is also thereby furnishing the information to
the Commission pursuant to Rule 12g3-2(b) under the Securities Exchange Act of
1934]

Yes No
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[If "Yes" is marked, indicate below the file number assigned to the
Registrant in connection with Rule 12g3-2(b): 82-_____]

Enclosure:

A press release dated April 13, 2000 announcing that
STMicroelectronics N.V. and Philips Semiconductors are expanding their existing
cooperation agreement.

[STMicroelectronics Logo]

[Philips Semiconductors Logo]

STMicroelectronics and Philips Semiconductors expand existing
cooperation agreement by building a new pilot line fab for deep-submicron
CMOS production on 12-inch wafers

Geneva and Eindhoven, April 13, 2000 - Philips Semiconductors, an affiliate of
Royal Philips Electronics (NYSE: PHG), and STMicroelectronics (NYSE: STM) will
invest \$700 million to jointly build an advanced 12-inch (300 mm) wafer
pilot-line fab in Crolles, France. This new agreement expands the existing
technological cooperation agreement that has been in place between these two
leading semiconductor companies since 1992.

By developing deep sub-micron semiconductor processes to 0.10 micron and below,
this new 12-inch pilot line will keep both companies at the forefront of
semiconductor technology. The pilot line will initially be designed to produce
up to 1000 wafers per week, with potential to ramp up to 2000 wafers per week as
needed. Site preparation and building of the pilot line fab will commence this
month, with the first 12-inch wafers expected to be processed in around two
years time.

"STMicroelectronics has a long track record of successful cooperation in several
areas of activity with customers, public research institutes and competitors,
particularly in the frame of European R&D programs such as JESSI and MEDEA,"
commented Pasquale Pistorio, President and CEO of STMicroelectronics. "Our
cooperation with Philips is an excellent example of the advantages of alliances
in leading edge R&D activities: it has certainly contributed to the
technological leadership of both companies and has helped ST to gain new

positions in the highly competitive semiconductor market."

"Critical investment in process technology is a cornerstone of our strategy to meet customer demand and satisfaction, and to keep us apace with the competition," said Arthur van der Poel, CEO, Philips Semiconductors. "The new process technologies resulting from this cooperation will further underpin our platform concept for realizing advanced ASICs and customer specific Systems-on-Silicon, while at the same time preparing both companies for the advent of 12-inch wafer processing. This new investment therefore means that Philips Semiconductors, together with STMicroelectronics, will quickly benefit from both the process and manufacturing advantages that accrue."

The decision to build the new facility follows several years of highly successful cooperation between the two companies, which has already given both of them access to 0.18 micron logic CMOS technology and manufacturing at ST's wafer fab in Crolles, France. The new 12-inch pilot-line fab will also be located in Crolles, with each company having equal access to both its research and development and manufacturing capabilities. In addition to developing shared CMOS processes at 0.12 micron, 0.10 micron and below, both companies will also be free to develop process technology options to suit their individual market focuses.

The cooperation between STMicroelectronics and Philips Semiconductors is in line with the ITRS (International Technology Roadmap for Semiconductors) roadmap and will address the two companies' markets that require advanced System-on-Chip technology. The cooperation will include advanced process technologies such as copper, low-k and high-k dielectrics, new transistor structures and other state-of-the-art process steps.

Standardization of libraries, design tools and process flows, which are already well aligned as a result of previous cooperation, will mean that new process technologies designed in the joint R&D and pilot line facility can be transferred directly into other STMicroelectronics and Philips fabs. This will ensure a fast ramp-up of production once these new processes come on-stream.

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The agreement between STMicroelectronics and Philips Semiconductors will be open to the contribution of other leading players in advanced semiconductor technology. In particular, ST will continue its very productive cooperation program with France Telecom R&D (formerly CNET) and with Leti (research lab of the French Commissariat a l'Energie Atomique-CEA) at the new joint pilot line in Crolles. Philips will contribute research results it obtains as a result of its recently agreed cooperation with IMEC of Louvain, Belgium.

Some of the above statements are forward-looking statements that involve a number of risks and uncertainties that could cause results to differ materially from current expectations. Among the factors are the following: new technology developments by the competition; capital requirements and availability of funding; intellectual property developments; manufacturing risks; changes in customer requirements; and international events.

About STMicroelectronics

STMicroelectronics (formerly SGS-THOMSON Microelectronics) is a global independent semiconductor company, whose shares are traded on the New York Stock Exchange, on the ParisBourse and on the Milan Stock Exchange. The Company designs, develops, manufactures and markets a broad range of semiconductor integrated circuits (ICs) and discrete devices used in a wide variety of microelectronic applications, including telecommunications systems, computer systems, consumer products, automotive products and industrial automation and control systems. In 1999, the Company's net revenues were \$5.056 billion and net earnings were \$547 million. Further information on ST can be found at www.st.com.

About Philips Semiconductors

Philips Semiconductors, which has annual revenues of approximately \$5 billion, designs and manufactures semiconductors and silicon systems platforms. Philips Semiconductors is spearheading the emerging field of systems on silicon solutions with the innovative Nexperia(TM) platform and VLSI Velocity(TM) tool set. The company's sea-of-IP(TM) design methodology allows plug and play intellectual property blocks for easily customizable products. The company is a leader in communications, consumer, PC peripherals and automotive semiconductors, which are key applications for convergence in end-user products. Philips Semiconductors is headquartered in Eindhoven, The Netherlands, and has operations throughout the world. For more information: www.philips.semiconductors.com.

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SIGNATURE

Pursuant to the requirements of the Securities Exchange Act of 1934, STMicroelectronics N.V. has duly caused this report to be signed on its behalf by the undersigned, thereunto duly authorized.

Date: April 19, 2000

STMicroelectronics N.V.

By: /s/ Pasquale Pistorio

Name: Pasquale Pistorio
Title: President and Chief
Executive Officer